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DL Technology



Viewpoint

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January 12, 2010

Jeanne Beacham, CEO, Delphon Industries

Well, the light at the end of the tunnel is no longer a train, but rather the bright new opportunities ahead for the industry.

Activity on all fronts has definitely picked up. Bookings steadily increased through the last quarter of 2009 and they are projected to continue growing throughout the coming year.

2010 will bring a change in the definition of "The Industry." The shift in market focus will continue to drive new products and new technology. We have already seen some of the impact related to the "Green Initiative" with Solar and LED advancements that need cost and efficiency improvements in semiconductors and packaging.

2010 will continue to see more emphasis in Medical Device and Electronics and Opto-electronics that will drive new equipment and the need for quick turn prototyping for advanced packaging and handling.

We believe that Delphon Industries is well positioned to take advantage of the growth in the market and to provide the necessary products and services through the Quik-Pak, Gel-Pak, TouchMark and UltraTape divisions.

Jeanne Beacham, CEO
Delphon Industries

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Jeanne Beacham, CEO, Delphon Industries](#)



Jeanne Beacham, CEO,
Delphon Industries

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January 21, 2010

Steve Adamson, Market Specialist, Nordson ASYMTEK

The world saw some traumatic times in 2009 and the electronics industry was quick to adapt to market changes. This enabled companies to save their core businesses and

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develop new products. At this year's 2010 Consumer Electronics Show in Las Vegas, we saw some interesting new products in the mobile and hand-held space. To get all the functions ...



January 20, 2010

Andy C. Mackie, Ph. D., MSc, Global Product Manager, Indium Corp.

In 2010, "green" is a necessity, not a value-proposition. Clarity on halogen-free issues is still being sought - there is no consistency in customers' requests in this area, even for materials that are cleaned. The Europeans will likely postpone the ELV move to Pb-free (lead-free) until the middle of the decade at least, but power semiconductor customers are still driving us in the direction of high-melting ...



January 19, 2010

Greg Wood, V.P., Sales & Marketing, Nordson ASYMTEK

Nordson ASYMTEK remains cautiously optimistic regarding economic recovery and growth in 2010. There are many positive signs including factory utilization and semiconductor sales-to-capital investment ratios, and we have certainly seen a significant upturn in business. However, we remain somewhat concerned about key global economic fundamentals such as the rate of recovery of the US employment market and the aggressive ...



January 18, 2010

Dr George T. Ayoub, President and CEO, Machine Vision Products, Inc.

With the world recovering from the current industry and general economic recession, companies that have continued investment and innovation over the downturn are poised for significant growth over 2010 and 2011. During 2009, we have made appreciable investments in inspection technologies and resources, this will continue into the future to allow growth in all aspects of our business. We will ...



January 14, 2010

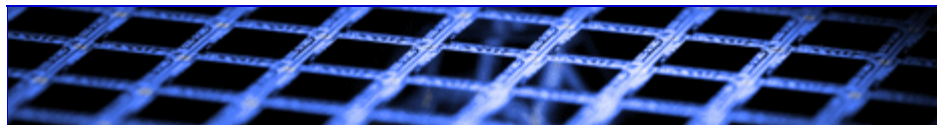
Lou Grice, Vice President of Marketing, Phoenix Contact

The economic malaise of 2009 will transform into a good, possibly great 2010 for semiconductor and related support industries. Low chip inventories and production capacity will be stretched by the burgeoning demand for next generation consumer electronics - from smart phones to gaming platforms to LCD flat-panel TVs. Stock and manufacturing undercapacity points to ...



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